

Product Summary

V_{RRM} (V)	I_O (A)	V_F Max (mV)	I_R Max (μ A) @ 20V
30	1	500	150

Description and Applications

The SDM1U30CP3 is a 30V 1A Schottky barrier rectifier that is optimized for very low forward voltage drop and low leakage current, housed in a compact die size surface mounted package that occupies only 0.6mm² board-space. The low thermal resistance enables designers to meet design challenges of increasing efficiency while at the same time reducing board space. It is ideally suited for use in portable applications such as:

- Blocking Diode
- Boost Diode
- Switching Diode
- Reverse Protection Diode

Features and Benefits

- Offboard Profile of 0.275mm—More than 30% Thinner Than DFN1006
- Very Low Forward Voltage (V_F) Minimizes Conduction Losses and Improves Efficiency
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

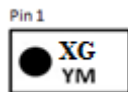
- Case: X3-DSN1006-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 (e4)
- Polarity: Cathode Dot
- Weight: 0.001 grams (Approximate)

Ordering Information (Note 4)

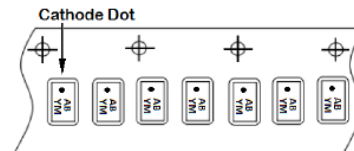
Part Number	Case	Packaging
SDM1U30CP3-7	X3-DSN1006-2	5000/Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



XG = Product Type Marking Code
 YM = Date Code Marking
 Y or \bar{Y} = Year (ex: E = 2017)
 M = Month (ex: 9 = September)
 Dot Denotes Cathode Pin



Date Code Key

Year	2016	2017	2018	2019	2020	2021	2022
Code	D	E	F	G	H	I	J

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Average Rectified Output Current	I _O	1	A
Repetitive Peak Forward Current (Pulse Wave = 1ms, Duty Cycle = 25%)	I _{FRM}	4	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	10	A

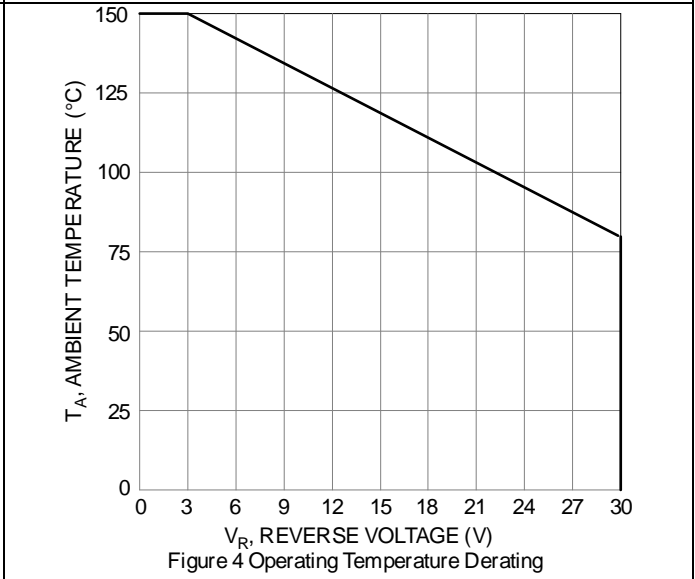
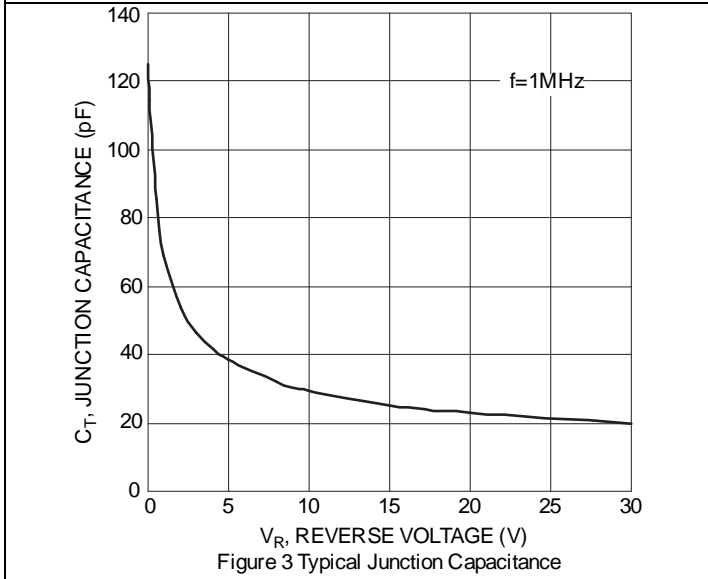
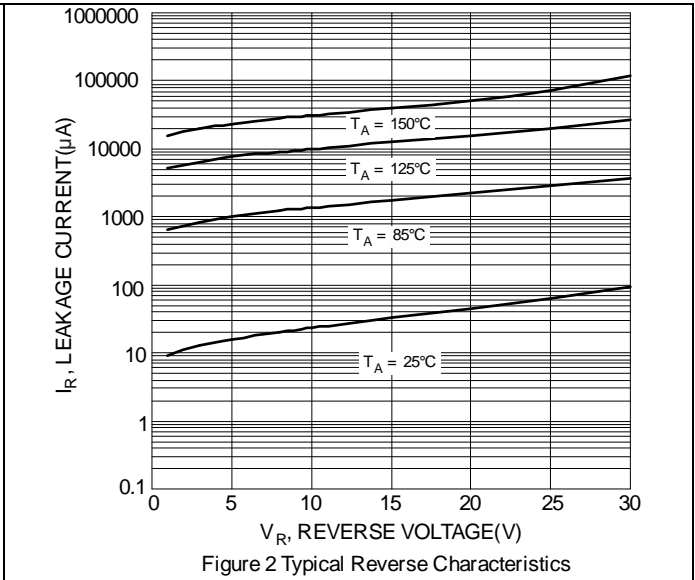
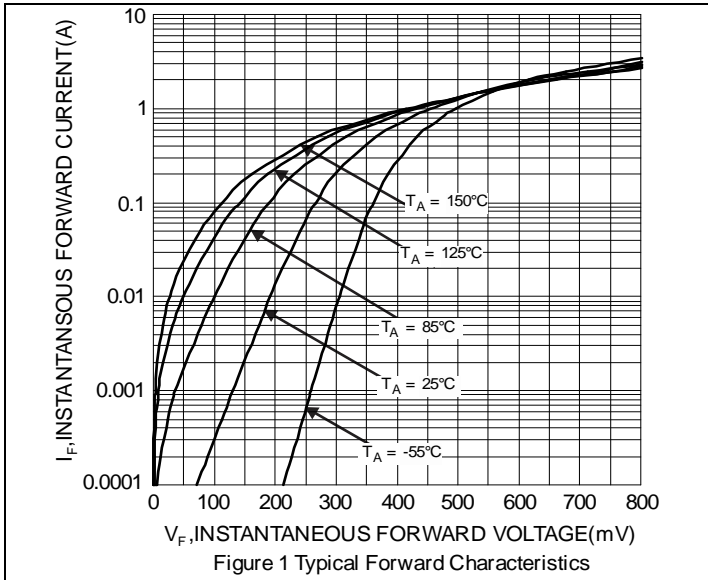
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	165	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	70	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage	V(BR)	30	—	—	V	I _R = 1mA
Forward Voltage Drop	V _F	—	267	325	mV	I _F = 0.1A, T _J = +25°C
		—	455	500		I _F = 1.0A, T _J = +25°C
Leakage Current (Note 7)	I _R	—	45	150	μA	V _R = 20V, T _J = +25°C
			95	350		V _R = 30V, T _J = +25°C
Junction Capacitance	C _T	—	69	—	pF	f = 1.0MHz, V _R = 1V
			29			f = 1.0MHz, V _R = 10V

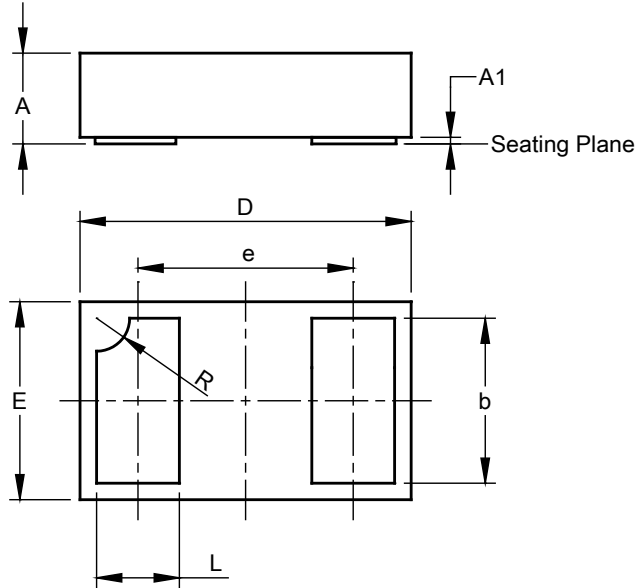
- Notes:
5. Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
 6. Device mounted on FR-4 PCB, 2oz. 1 square inch Copper.
 7. Short duration pulse test used to minimize self-heating effect.



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X3-DSN1006-2

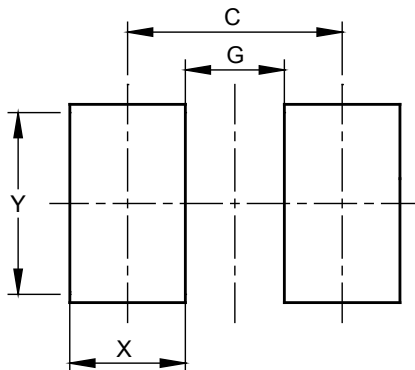


X3-DSN1006-2			
Dim	Min	Max	Typ
A	0.25	0.30	0.275
A1	0.00	0.02	--
b	0.48	0.52	0.50
D	0.95	1.05	1.00
E	0.55	0.65	0.60
e	--	--	0.65
L	0.23	0.27	0.25
R	--	--	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X3-DSN1006-2



Dimensions	Value (in mm)
C	0.65
G	0.30
X	0.35
Y	0.60

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